

Description

The HSMF-C118 tricolor chip-type LED is designed in an ultra small package for miniaturization. It is the first of its kind to achieve such small packaging for 3 dies. With the freedom to have any combination of colors from mixing of the 3 primary colors, this will yield a wide variety of colors to suit every application and product theme.

The small size, narrow footprint, and low profile make this LED excellent for back-lighting, status indication, and front panel illumination applications.

In order to facilitate pick and place operation, this ChipLED is shipped in tape and reel, with 3000 units per reel. The package is compatible with IR soldering and binned by both color and intensity.

Features

- Common anode
- Small 3.2 x 2.7 x 1.1 mm package
- Diffused optics
- Red/Green/Blue color combination
- Available in 8 mm tape on 7 inch (178 mm) diameter reels
- High brightness using AllnGaP and InGaN die technology
- Compatible with reflow soldering

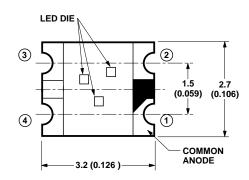
Applications

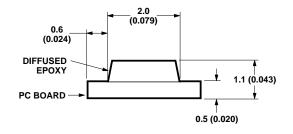
- Backlighting
- Status indicator
- Front panel indicator
- Office automation, home appliances, industrial equipment

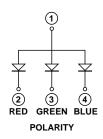
CAUTION: HSMF-C118 is Class 1 ESD sensitive per MIL-STD-1686. Please observe appropriate precautions during handling and processing. Refer to Agilent Technologies Application Note AN-1142 for additional details.

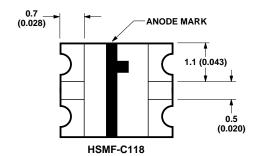


Package Dimensions









- NOTES:
 1. DIMENSIONS IN MILLIMETERS (INCHES).
 2. TOLERANCE ± 0.1 mm (± 0.004 IN.) UNLESS OTHERWISE NOTED.

Absolute Maximum Ratings at $T_A = 25^{\circ}C$

Parameter	AlinGaP Red	InGaN Green	InGaN Blue	Units
DC Forward Current ^[1, 3, 4]	20	20	20	mA
Power Dissipation ^[1]	48	78	78	mW
DC Forward Current ^[2]	15	15	15	mA
Power Dissipation ^[2]	36	59	59	mW
Reverse Voltage (I _R = 100 μA)	5	5	5	V
LED Junction Temperature	95	95	95	°C
Operating Temperature Range			°C	
Storage Temperature Range	-40 to +85			°C
Soldering Temperature	See IR soldering profile (Figure 6)			

Notes:

- 1. Applies when single LED is lit up.
- 2. Applies when all 3 LEDs are lit up simultaneously.
- 3. Derate linearly as shown in Figure 4.
- 4. Drive currents above 5 mA are recommended for best long term performance.

Electrical Characteristics at T_A = 25°C

	Forward Voltage V _F (Volts) @ I _F = 20 mA		Reverse Breakdown V _R (Volts) @ I _R = 100 μA	Capacitance C (pF), @ V _F = 0, f = 1 MHz	Thermal Resistance R _{OJ-PIN} (°C/W)
Color	Тур.	Max.	Min.	Тур.	Тур.
AllnGaP Red	1.9	2.4	5	17	400
InGaN Green	3.5	3.9	5	110	450
InGaN Blue	3.5	3.9	5	110	450

Optical Characteristics at $T_A = 25^{\circ}C$

		us Intensity) @ I _F = 20 mA ^[1]	Peak Wavelength λ _{peak} (nm)	$\begin{array}{c} \textbf{Color,} \\ \textbf{Dominant} \\ \textbf{Wavelength} \\ \lambda_{\textbf{d}}^{[2]} \text{ (nm)} \end{array}$	Viewing Angle 2 θ _{1/2} Degrees ^[3]	Luminous Efficacy ην (Im/W)
Color	Min.	Тур.	Тур.	Тур.	Тур.	Тур.
AlInGaP Red	25	90	637	626	135	155
InGaN Green	40	120	523	525	130	490
InGaN Blue	10	40	468	470	125	80

Notes:

- 1. The luminous intensity, I_v, is measured at the peak of the spatial radiation pattern which may not be aligned with the mechanical axis of the lamp package.
- 2. The dominant wavelength, λ_d , is derived from the CIE Chromatically Diagram and represents the perceived color of the device.
- 3. $\theta_{1/2}$ is the off-axis angle where the luminous intensity is 1/2 the peak intensity.

CAUTION:

- 1. The above optical performance specifications are valid in the case when single LED is lit up.
- The above product specifications DO NOT provide any guarantee on color mixing, color consistency over time, or uniformity in luminous intensity when more than 1 LED is lit.
- 3. Please refer to Agilent
 Technologies' *Application Brief AB D-007* for additional details/explanation on driving the part in parallel circuit.

Intensity (I_v) Bin Limits^[1]

	Intensity (mcd)				
Bin ID	Min.	Max.			
L	11.20	18.00			
M	18.00	28.50			
N	28.50	45.00			
P	45.00	71.50			
Q	71.50	112.50			
R	112.50	180.00			

Tolerance: \pm 15%.

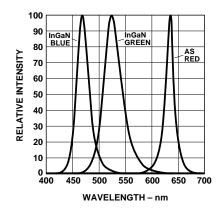


Figure 1. Relative intensity vs. wavelength.

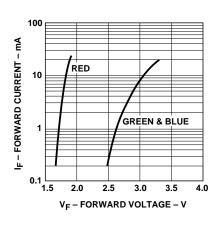


Figure 2. Forward current vs. forward voltage.

Color Bin Limits^[1]

	Blue Color Bins Dom. Wavelength (nm)			
Bin ID	Min.	Max.		
A	460.0	465.0		
В	465.0	470.0		
С	470.0	475.0		
D	475.0	480.0		

 $Tolerance: \pm\,1\;nm$

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Figure 3. Luminous intensity vs. forward

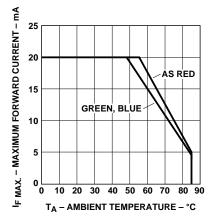


Figure 4. Maximum forward current vs. ambient temperature (1 chip lit up).

Red Color Bins Dom. Wavelength (nm) Bin ID Min. Max. - 615.0 630.0

 $Tolerance: \pm \ 1 \ nm$

	Green Color Bins Dom. Wavelength (nm)			
Bin ID	Min.	Max.		
A	515.0	520.0		
В	520.0	525.0		
С	525.0	530.0		
D	530.0	535.0		

 $Tolerance: \pm\,1\;nm$

Note:

 Bin categories are established for classification of products. Products may not be available in all categories. Please contact your Agilent representative for information on currently available bins.

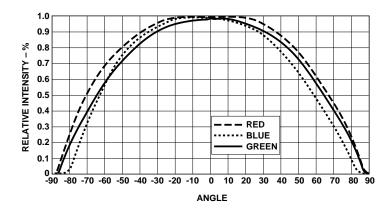


Figure 5. Relative intensity vs. angle.

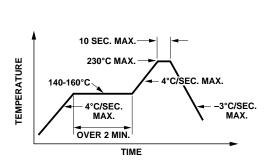
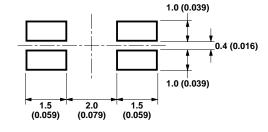


Figure 6. Recommended reflow soldering profile.



NOTE:
1. ALL DIMENSIONS IN MILLIMETERS (INCHES).

Figure 7. Recommended soldering pattern.

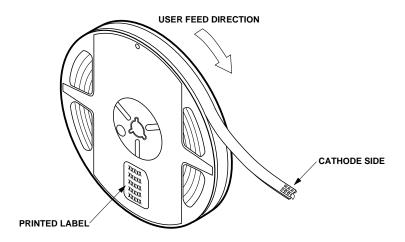
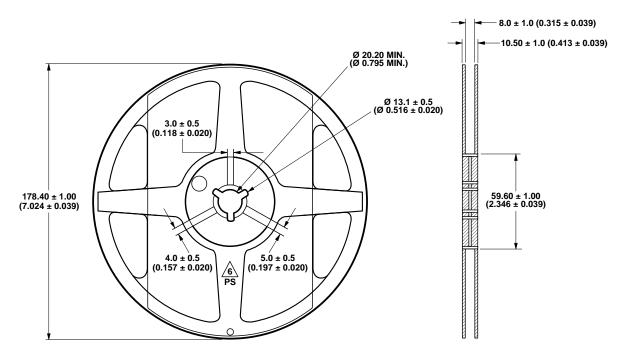


Figure 8. Reeling orientation.



NOTE:
1. ALL DIMENSIONS IN MILLIMETERS (INCHES).

Figure 9. Reel dimensions.

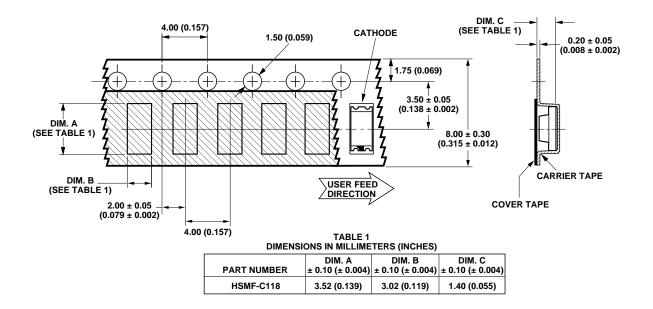


Figure 10. Tape dimensions.

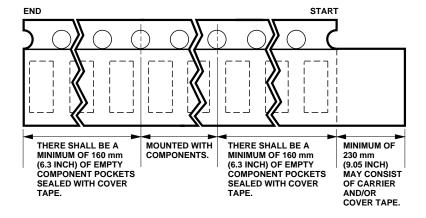


Figure 11. Tape leader and trailer dimensions.

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS (INCHES). 2. TOLERANCE IS \pm 0.1 mm (\pm 0.004 IN.) UNLESS OTHERWISE SPECIFIED.

Convective IR Reflow Soldering

For more information on IR reflow soldering, refer to Application Note 1060, Surface Mounting SMT LED Indicator Components.

Storage Condition:

5 to 30°C @ 60% RH max.

Baking is required under the condition:

- a) the blue silica gel indicator becoming white/transparent
- b) the pack has been opened for more than 1 week

Baking recommended condition: 60 ± 5 °C for 20 hours.

www.agilent.com/semiconductors

For product information and a complete list of distributors, please go to our web site.

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